

What is claimed is:

1. A heat-dissipation structure of a plasma display panel device including a plasma display panel and a drive circuit for driving
5 the plasma display panel, comprising:

a plurality of circuit boards; and

electronic components making up the drive circuit and mounted separately on said plurality of circuit boards.

- 10 2. The heat-dissipation structure of the plasma display panel according to claim 1, wherein an electronic component with the heat-generating property out of said electronic components making up the drive circuit is mounted on a required circuit board out of said plurality of circuit boards.

- 15 3. The heat-dissipation structure of the plasma display panel device according to claim 2, wherein said required circuit board is supported by a metal-made build-up frame thermally-conductively installed on a metal-made casing of the plasma display panel device
20 and being in contact with at least part of said electronic components with the heat-generating property mounted on the required circuit board.

- 25 4. The heat-dissipation structure of the plasma display panel according to claim 3, wherein said electronic components with said heat-generating property are mounted separately on both faces of said required circuit board, and the electronic component mounted

on one face of the required circuit board are in contact with said build-up frame.

5. The heat-dissipation structure of the plasma display panel according to claim 4, wherein said electronic component mounted on the one face of said required circuit board and being in contact with said build-up frame is a heat-generating module.

6. The heat-dissipation structure of the plasma display panel according to claim 2, wherein part of the electronic components with the heat-generating property out of said electronic components making up the drive circuit is mounted on said required circuit board out of said plurality of circuit boards, and another electronic component with the heat-generating property is mounted on a circuit board out of said plurality of circuit boards other than said required circuit board while being in thermal-conductive contact with a metal-made casing of the plasma display panel device.

7. The heat-dissipation structure of the plasma display panel according to claim 7, wherein said another electronic component with the heat-generating property is thermal-conductively installed to the metal-made casing of the plasma display panel device and is in contact with a metal-made build-up frame supporting said required circuit board.

8. The heat-dissipation structure of the plasma display panel according to claim 6, wherein said another electronic components

with the heat-generating property are a heat-generating module.

9. A heat-dissipation structure of a plasma display panel including
a plasma display panel and a drive circuit for driving the plasma
5 display panel, comprising electronic components making up the drive
circuit and mounted separately on both faces of a circuit board.

10. The heat-dissipation structure of the plasma display panel
according to claim 9, wherein said circuit board having both the
10 faces on which said electrode components are separately mounted is
supported by a metal-made build-up frame, installed
thermal-conductively to a metal-made casing of the plasma display
panel device and being in contact with part of at least the electronic
components with the heat-generating property out of the electronic
15 components mounted on the circuit board.

11. The heat-dissipation structure of the plasma display panel
according to claim 10, wherein the electronic component mounted on
said circuit board and being in contact with the build-up frame is
20 a heat-generating module.